



L	Hits	Search Text	DB	Time stamp
Number	11105	Scarcii Text	DB .	Time Stamp
1	4666	(HF or hydrofluoric) and (nitric or	USPAT;	2003/01/20
_	1000	"HNO.sub.3") and acetic	EPO; JPO;	08:48
		into toubis y and decere	IBM TDB	00.40
4	2230	(HF or hydrofluoric) same (nitric or	USPAT;	2003/01/20
•		"HNO.sub.3") same acetic	EPO; JPO;	08:19
		involution, band describ	IBM TDB	00.19
3 ,	397	"semiconductor die" same etch\$5	USPAT;	2003/01/20
1 ,		James States	EPO; JPO;	07:28
			IBM TDB	07.20
6	500	"semiconductor die" same (thinned or	USPAT;	2003/01/20
		thinning or thin)	EPO; JPO;	07:28
		,,	IBM TDB	
8	19	("semiconductor die" same (thinned or	USPAT;	2003/01/20
		thinning or thin)) and (HF or	EPO; JPO;	07:29
		hydrofluoric) and (nitric or "HNO.sub.3")	IBM TDB	0,.23
		,	12	
2	632	(die or chip) same (thinned or thinning)	USPAT;	2003/01/20
		same semiconductor	EPO; JPO;	08:08
			IBM TDB	
12	5461	(die or dice) same etch\$4	USPAT;	2003/01/20
			EPO; JPO;	08:15
			IBM TDB	
13	57	((die or dice) same etch\$4) and ((HF or	USPAT;	2003/01/20
		hydrofluoric) and (nitric or "HNO.sub.3")	EPO; JPO;	08:09
		and acetic)	IBM TDB	
14	2609	(die or dice) with etch\$4	USPAT;	2003/01/20
			EPO; JPO;	08:16
			IBM_TDB	
15 .	2448	die with etch\$4	USPAT;	2003/01/20
			EPO; JPO;	08:37
			IBM_TDB	
17	138	((HF or hydrofluoric) same (nitric or	USPAT;	2003/01/20
		"HNO.sub.3") same acetic) and die	EPO; JPO;	08:24
			IBM_TDB	
19	794	die with (thinned or thinning)	USPAT;	2003/01/20
			EPO; JPO;	08:38
			IBM_TDB	
20	196		USPAT;	2003/01/20
		hydrofluoric) and (nitric or "HNO.sub.3")	EPO; JPO;	08:48
		and acetic	IBM_TDB	